- **Can Be Used as a 4-Bit Digital Comparator**
- **Input Clamping Diodes Simplify System Design**
- **Fully Compatible with Most TTL Circuits**

FUNCTION TABLE

INPUTS		OUTPUT
A	B	Y
L	L	H
L	H	L
H	L	L
H	H	H

H = high level, L = low level

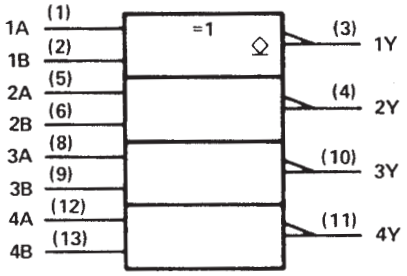
description

The 'LS266 is comprised of four independent 2-input exclusive-NOR gates with open-collector outputs. The open-collector outputs permit tying outputs together for multiple-bit comparisons.

logic symbol (each gate)



logic symbol†

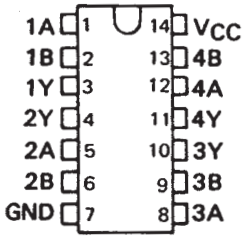


positive logic: $Y = \overline{A \oplus B} = AB + \overline{A}\,\overline{B}$

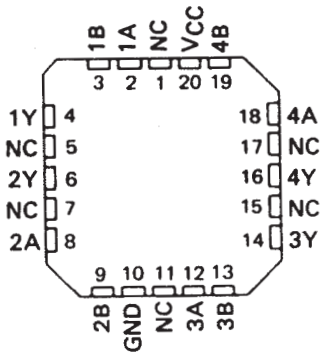
† This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN54LS266 . . . J OR W PACKAGE
SN74LS266 . . . D OR N PACKAGE
(TOP VIEW)

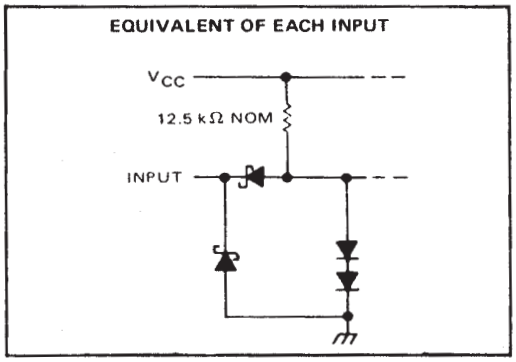


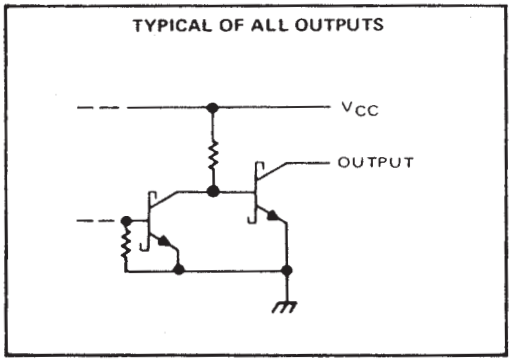
SN54LS266 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

schematic of inputs and outputs





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Operating free-air temperature range: SN54LS266 . . . . . −55°C to 125°C
SN74LS266 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54LS266			SN74LS266			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output voltage, V_{OH}			5.5			5.5	V
Low-level output current, I_{OL}			4			8	mA
Operating free-air temperature, T_A	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54LS266			SN74LS266			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage			2			2			V
V_{IL}	Low-level input voltage					0.7			0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = −18 mA			−1.5			−1.5	V
I_{OH}	High-level output current	V_{CC} = MIN, V_{IL} = V_{IL} max,	V_{IH} = 2 V, V_{OH} = 5.5 V			100			100	μA
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL} max	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
			I_{OL} = 8 mA					0.35	0.5	
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 7 V			0.2			0.2	mA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.7 V			40			40	μA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.4 V			−0.8			−0.8	mA
I_{CC}	Supply current	V_{CC} = MAX,	See Note 2		8	13		8	13	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
NOTE 2: I_{CC} is measured with one input of each gate at 4.5 V, the other inputs grounded, and the outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER§	FROM (INPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	A or B	Other input low	C_L = 15 pF, R_L = 2 kΩ, See Note 3		18	30	ns
t_{PHL}					18	30	
t_{PLH}	A or B	Other input high			18	30	ns
t_{PHL}					18	30	

§t_{PLH} = propagation delay time, low-to-high-level output
t_{PHL} = propagation delay time, high-to-low-level output
NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN54LS266J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS266J	Samples
SN74LS266D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS266	Samples
SN74LS266DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS266	Samples
SN74LS266DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS266	Samples
SN74LS266N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS266N	Samples
SN74LS266N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS266NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS266N	Samples
SN74LS266NSR	OBSOLETE	SO	NS	14		TBD	Call TI	Call TI	0 to 70	74LS266	
SN74LS266NSRE4	OBSOLETE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		
SN74LS266NSRG4	OBSOLETE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		
SNJ54LS266FK	OBSOLETE			20		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS266J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS266J	Samples
SNJ54LS266W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS266W	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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OTHER QUALIFIED VERSIONS OF SN54LS266, SN74LS266 :

- Catalog: SN74LS266
- Military: SN54LS266

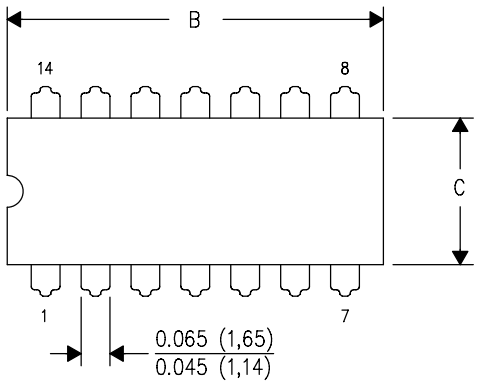
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

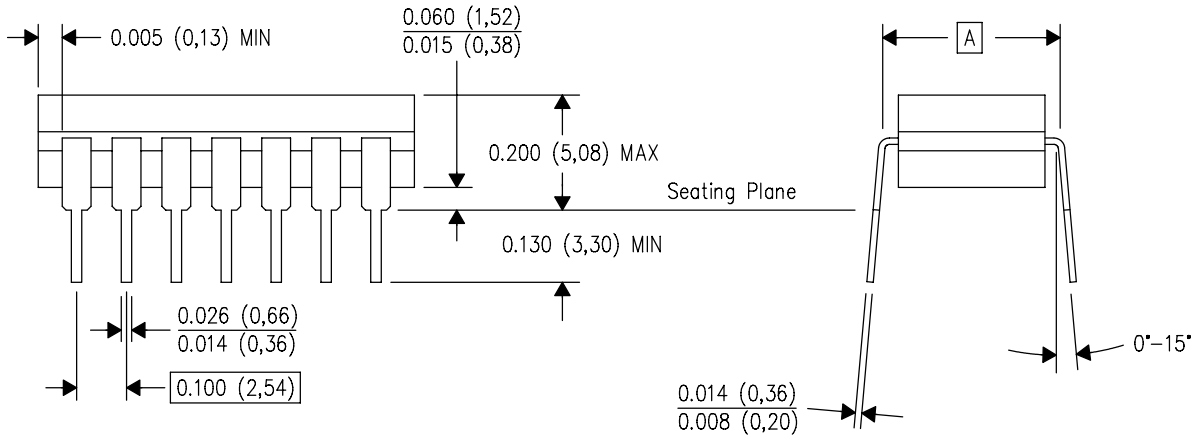
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



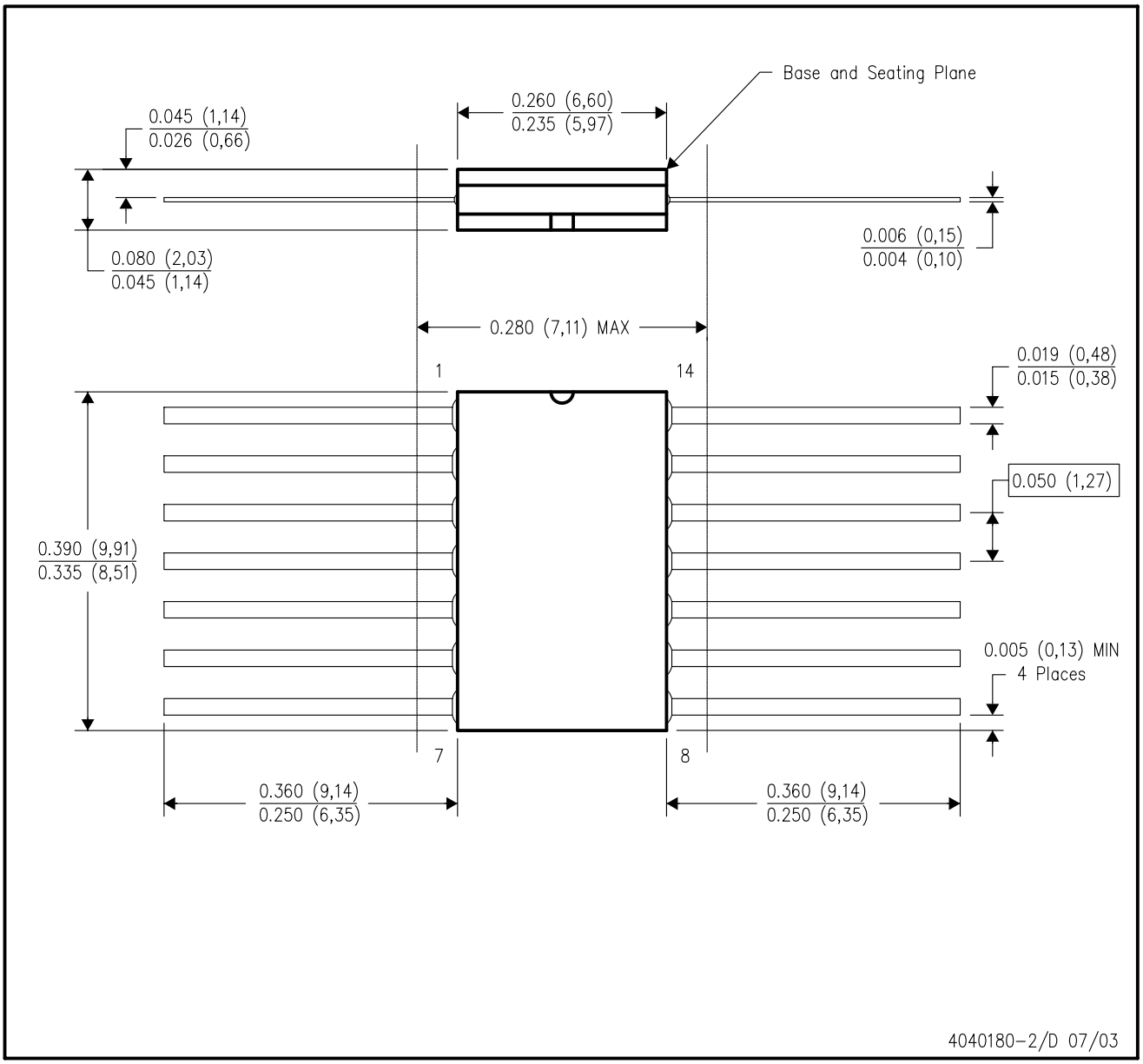
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

W (R–GDFP–F14) CERAMIC DUAL FLATPACK

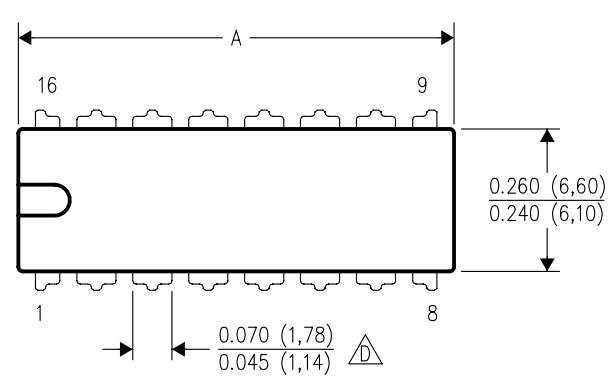


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14 and JEDEC MO–092AB

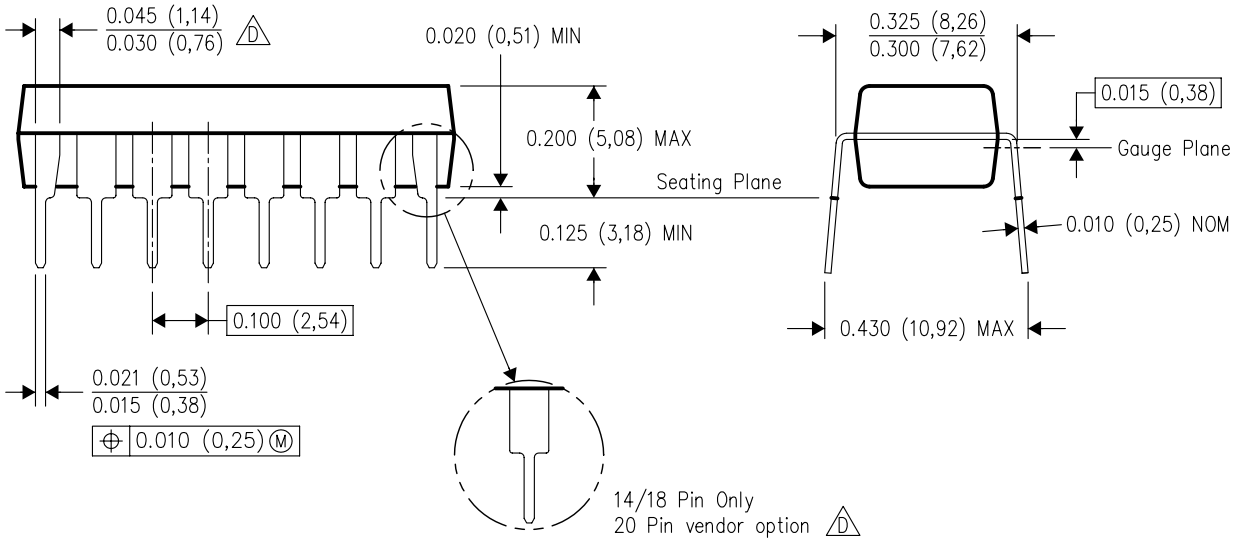
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



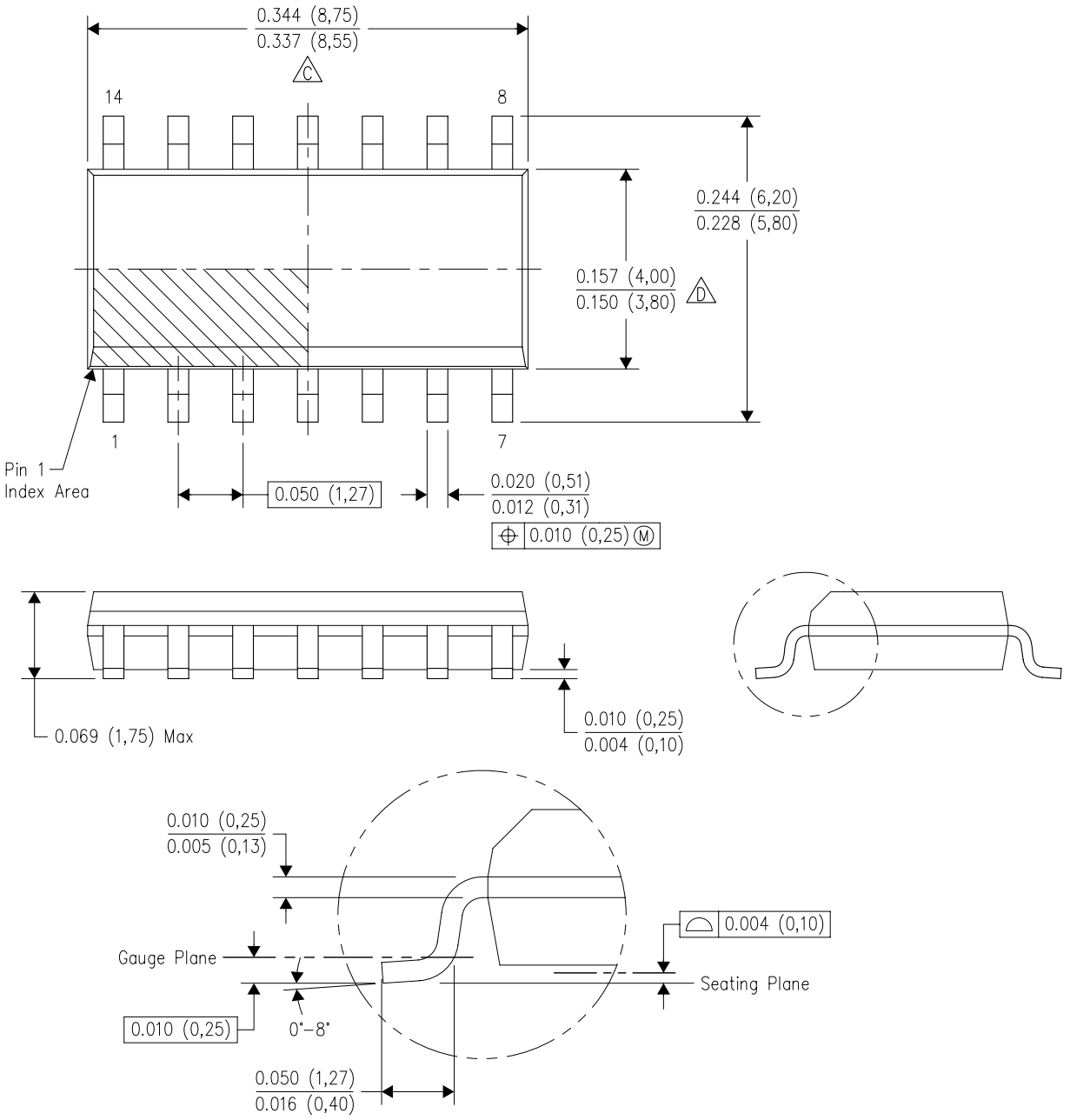
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

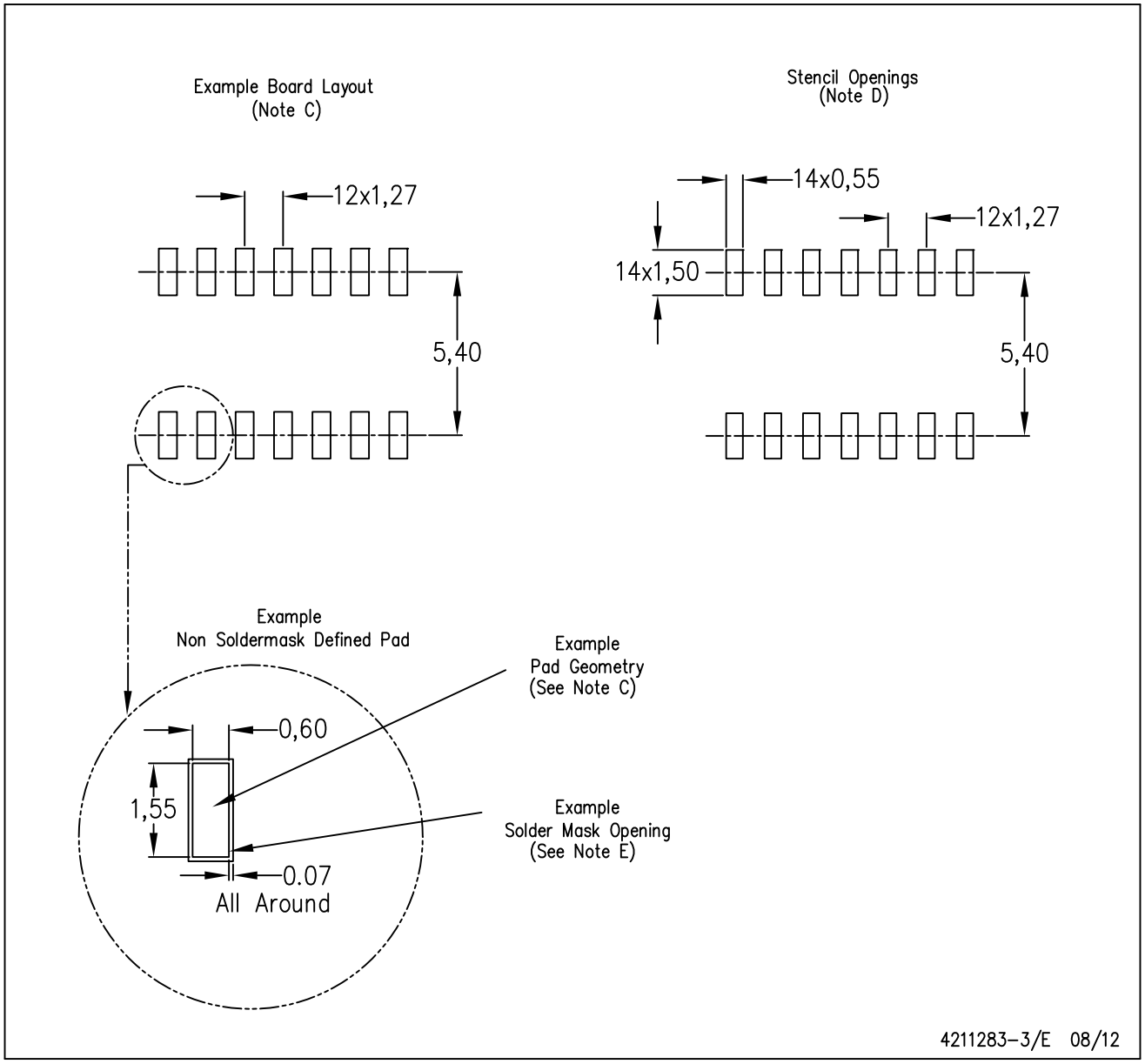
D (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040047–5/M 06/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE

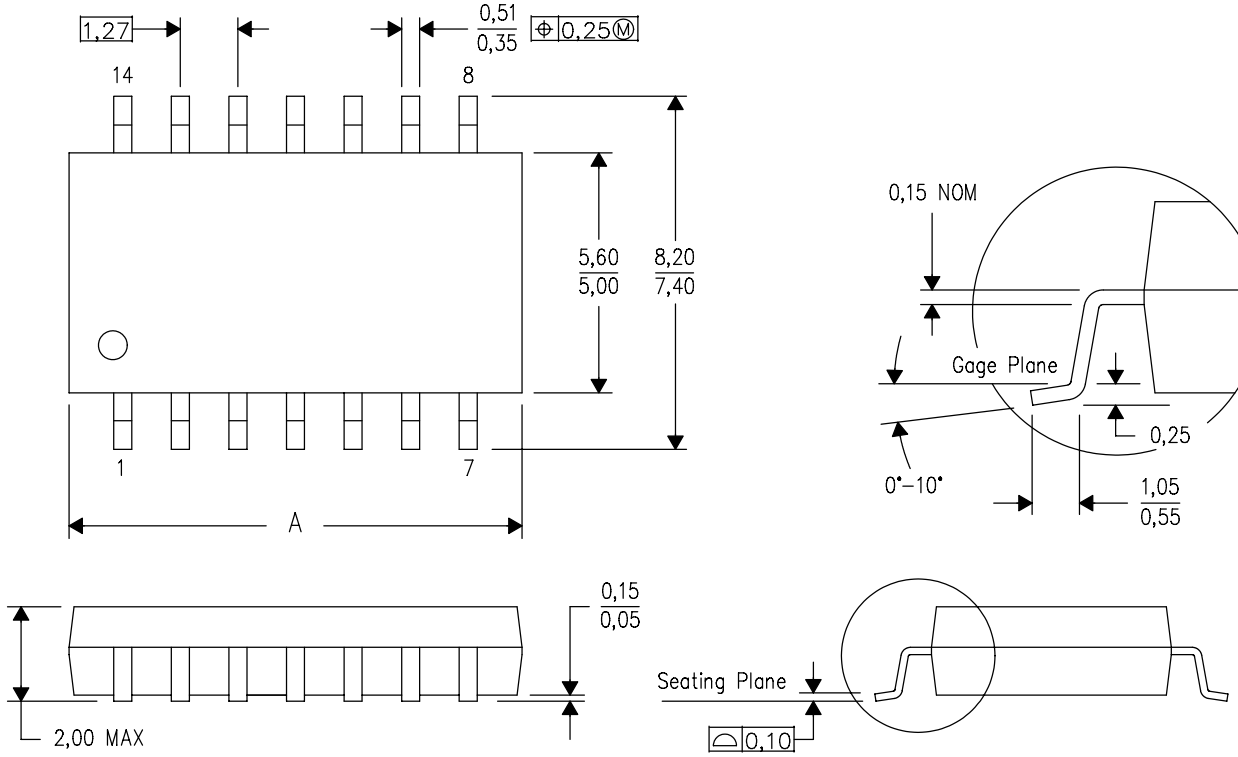


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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